

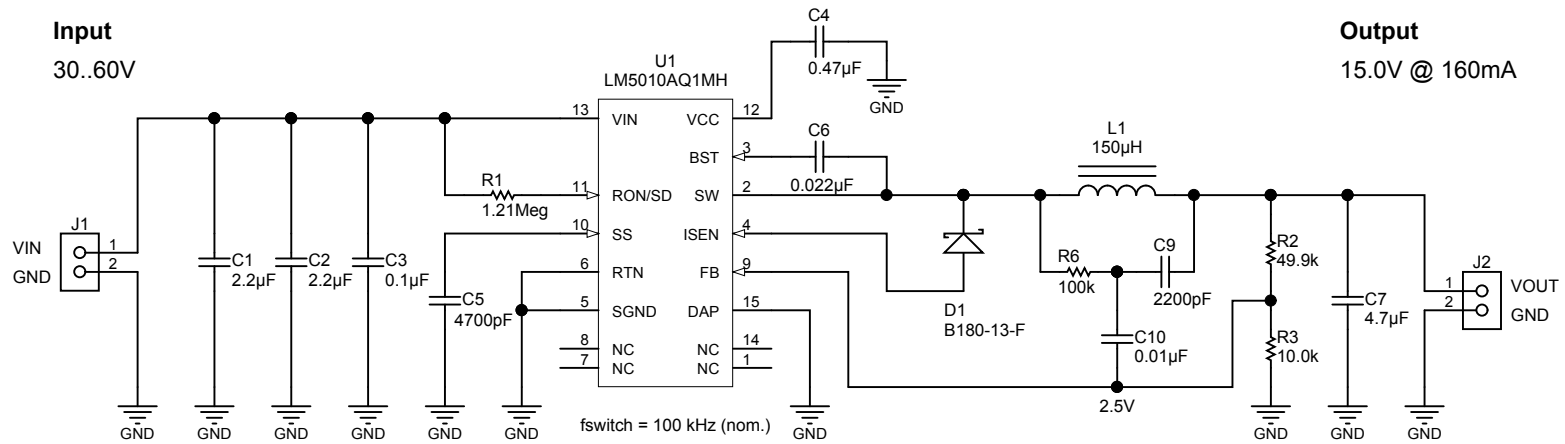
Design Notes

- * Converter is working in discontinuous conduction mode
- * Duty cycle is 16.41%
- * Modified LM5010A EVM

- * D1: 500mA peak, 200mA rms, 120mA avg
- * L1: 500mA peak, 230mA rms

Revision History

Revision	Notes
A	* Paper Draft
B	* Built & Tested



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Number: PMP8660 Rev: B
 SVN Rev: Not in version control
 Drawn By:
 Engineer: Matthias Ulmann

Designed for: Public Release Mod. Date: 7/24/2013
 Project Title: 30..60V -> 15.0V @ 160mA
 Sheet Title:
 Assembly Variant: Variant name not interpreted Sheet: 1 of 1
 File: PMP8660RevB.SchDoc Size: A4
 Contact: <http://www.ti.com/support>



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